

a1 1. (Amended) A case for dissipating heat from an electronic device, comprising:  
an electronic circuit board;  
a heat generating electronic component disposed on said circuit board; and  
a housing positioned about said electronic circuit board and said heat generating  
electronic component; said housing being made of a net-shaped moldable thermally  
conductive composite material of a polymer base matrix with thermally conductive filler  
therein; said housing being in thermal communication with said electronic component  
with heat being dissipating from said heat generating electronic component and through  
said housing.

a2 5. (Amended) A case for dissipating heat from an electronic device, comprising:  
4 an electronic circuit board;  
a heat generating electronic component disposed on said circuit board;  
a housing positioned about said electronic circuit board and said heat generating  
electronic component; said housing being of a net-shaped moldable thermally  
conductive composite material of a polymer base matrix with thermally conductive filler  
therein;  
a protrusion emanating from said housing corresponding and aligned with said  
heat generating electronic component; said protrusion emanating from said housing;  
and  
said protrusion being in thermal communication with said electronic component  
with heat being dissipating from said heat generating electronic component and through  
said housing via said protrusion.

938. (Amended) A case for dissipating heat from an electronic device, comprising:  
an electronic circuit board;  
a heat generating electronic component, having a top surface, disposed on said  
circuit board;  
an electromagnetic interference shield positioned on said electronic circuit board  
with said heat generating electronic component residing therebetween; said  
electromagnetic interference shield including a top surface with an aperture  
therethrough;  
a heat transfer conduit molded into and through said aperture; said heat transfer  
conduit being made of a thermally conductive material and having a top surface and a  
bottom surface;  
a housing, being made of a net-shaped moldable thermally conductive  
composite material of a polymer base matrix with thermally conductive filler therein,  
being in thermal communication with said top surface of said heat transfer conduit; said  
bottom surface of said heat transfer conduit being in thermal communication with said  
top surface of said heat generating electronic component;  
whereby heat is dissipated from said from said heat generating electronic  
component via said heat transfer conduit through said electromagnetic interference  
shield and out said housing while said electromagnetic interference shield protects said  
heat generating electronic component from electromagnetic interference.

#### REMARKS

Claims 1, 5 and 9 have been amended and Claims 2, 6 and 10 have been  
canceled. Claims 1, 3-5 and 7-9, 11 and 12 now remain pending in this application.